



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

David A. Kiss

Serial No.: 10/017,031

Filed: October 30, 2001

For: Packaged Combination Memory
for Electronic Devices

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Art Unit: 2815

Examiner: Sheila Clark

Atty Docket: ITL.0696US
P13281

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Commissioner for Patents
Washington, DC 20231

REPLY TO FINAL REJECTION

Sir:

In response to the final office action mailed October 22, 2002, reconsideration is requested in view of the following remarks.

REMARKS

Claim 1 calls for a circuit that is packaged and includes a processor, a volatile memory, and a cross point memory. Clearly and indisputably, the Mauritz patent does not teach a packaged structure. Mauritz is explicit for example, in the Figure on the first page, that different chips 24, 26, 22, and 12 are used. There is no indication of an intent to package the disparate memory elements into the same package.

With the single package solution, a one packaged component solves all problems approach may be provided. In other words, regardless of the application, a single packaged integrated circuit may be supplied and may be able to handle essentially any type of memory application. Packaging all of these different functionalities into the same package is nowhere suggested in Mauritz.

Date of Deposit: November 4, 2002

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington DC 20231.

Cynthia L. Hayden
Cynthia L. Hayden

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